TE Internal #: 2-2822979-4

LGA Sockets, LGA 3647, Board-to-Board, 3647 Position, Gold,

Contact Mating Area Plating Material Thickness 30 µin

View on TE.com >



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 SOCKETS



IC Socket Type: LGA 3647

Connector System: Board-to-Board

Number of Positions: 3647

Contact Mating Area Plating Material: Gold

Contact Mating Area Plating Material Thickness: [30 µin]

All LGA 3647 SOCKETS (8)

### **Features**

### **Product Type Features**

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

### **Configuration Features**

Number of Positions	3647
Grid Spacing	.9906 x .8585 mm[.039 x .0338 in]

### **Body Features**

Frame Style	Square
Plating Material	Gold
Plating Thickness	30 μin

#### **Contact Features**

Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
Contact Mating Area Plating Material	Gold
	30 μin
Contact Current Rating (Max)	.5 A

### **Mechanical Attachment**



Heat Sink Attachment	Without
PCB Mounting Style	Surface Mount Solder Ball
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.86 mm, .99 mm[.034 in][.039 in]
Housing Material	High Temperature Thermoplastic
Housing Color	Black
Usage Conditions	
Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tray
Other	
Comment	Lead-Free Solderball

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUN 2016 (169) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

## Compatible Parts





IFP/LEC CBL ASSY 2 PORT TYPE A STR









# Customers Also Bought













TE Part #1-2324271-7 RIGHT SEGMENT LGA4189-5 SOCKETP5 FOR ODM











### **Documents**

### **Product Drawings**

LGA3647-1 SOCKET-P1 KIT FOR ODM (30U AU)

English

### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2-2822979-4\_C.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2-2822979-4\_C.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2-2822979-4\_C.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

### Datasheets & Catalog Pages

LGA 3647 Socket Product Flyer

English

### **Product Specifications**

**Application Specification** 

English